

Special Issue on Thermal Analysis Method

Call for Papers

Thermal Analysis is a branch of materials science where the properties of materials are studied as they change with temperature. In 1977, the International Confederation for Thermal Analysis defined Thermal Analysis as: Thermal Analysis is a technology that measures the variation of physical properties of the substance with the temperature in the condition of programmed temperature. The most commonly Thermal Analysis Methods are: Dielectric thermal analysis (DEA), Differential thermal analysis (DTA), Differential scanning calorimetry (DSC), Dilatometry (DIL), Dynamic mechanical analysis (DMA), Evolved gas analysis (EGA), Laser flash analysis (LFA), Thermogravimetric analysis (TGA), Thermomechanical analysis (TMA), Thermo-optical analysis (TOA).

In this special issue, we intend to invite front-line researchers and authors to submit original research and review articles on exploring **Thermal Analysis Method**.

Authors should read over the journal's [Authors' Guidelines](#) carefully before submission, Prospective authors should submit an electronic copy of their complete manuscript through the journal [Paper Submission System](#).

Please kindly notice that the "**Special Issue**" under your manuscript title is supposed to be specified and the research field "**Special Issue —Thermal Analysis Method**" should be chosen during your submission.

According to the following timetable:

Manuscript Due	May 10th, 2013
Publication Date	July 2013

Special Issue Editor

Guest Editor:

For further questions or inquiries

Please contact Editorial Assistant at

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